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Docket No.: M1071.1931  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Takatoshi Kato et al.

Application No.: 10/534,460

Confirmation No.: 7019

Filed: February 19, 2006

Art Unit: 2817

For: LINE TRANSITION, HIGH FREQUENCY  
MODULE, AND METHOD FOR  
MANUFACTURING LINE TRANSITION

Examiner: B. T. Lee

**RESPONSE TO RESTRICTION REQUIREMENT**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the restriction requirement set forth in the Office Action mailed August 30, 2006 (Paper No. 20060825), Applicants hereby provisionally elect claims 1, 2 and 4-6 for continued examination, with traverse.

The Examiner has required restriction between the invention defined by Group I (claims 1, 2 and 4-6) drawn to a line transition, classified in class 333, subclass 26; and Group II (claim 3) drawn to a method of manufacturing a line transition. The Examiner has reasoned that the above-noted restriction is proper because, in the instant

case, the product can be made by another and materially different process such as molding the dielectric substrate to the desired shape, as to include the notch. Based on currently known manufacturing methods, Applicants respectfully disagree and traverse the same.

The Commissioner may require restriction if two or more independent and distinct inventions are claimed in a single application (37 CFR 1.142(a)). In the present case, although the claimed subject matter may be classified in different classes, the inventions are not independent.

The purpose of the present invention is to provide a line transition in which a variation in the positional relationship between a coupled-line pattern segment formed on a dielectric substrate and the corresponding edge of the dielectric substrate is minimized so as to stabilize the characteristics of the planar-circuitry to waveguide transition.

With currently known manufacturing methods, the line transition of the Group I invention can be only made by the process of the Group II invention. When the notches are formed as through holes prior to firing the motherboard, the positional relationship between each coupled-line pattern segment and the notch arranged in the vicinity of the coupled-line pattern segment at the edge of the corresponding dielectric substrate is not affected by the displacement of the dicing lines. Any other currently known process would create a line transition having a large variation in the above-noted positional relationship.

If the Examiner is aware of another method to make the product as claimed, using a process which is materially different from that set forth in the restricted claims, Applicants respectfully request the Examiner to substantiate his position in greater detail. Otherwise, it is respectfully requested that the restriction requirement be withdrawn, and that each of claims 1-6 presently pending in this application be examined.

Dated: September 27, 2006

Respectfully submitted,

By Richard LaCava

Richard LaCava

Registration No.: 41,135

DICKSTEIN SHAPIRO LLP

1177 Avenue of the Americas

41st Floor

New York, New York 10036-2714

(212) 277-6500

Attorney for Applicant